

Z21 ■ Install label in silkscreened box after final wash. Text shall be 8 pt font. Text shall be per the Label Table in the PDF schematic.

Z22 ■ These assemblies are ESD sensitive, ESD precautions shall be observed.

Z23 ■ These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

Z24 ■ These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.

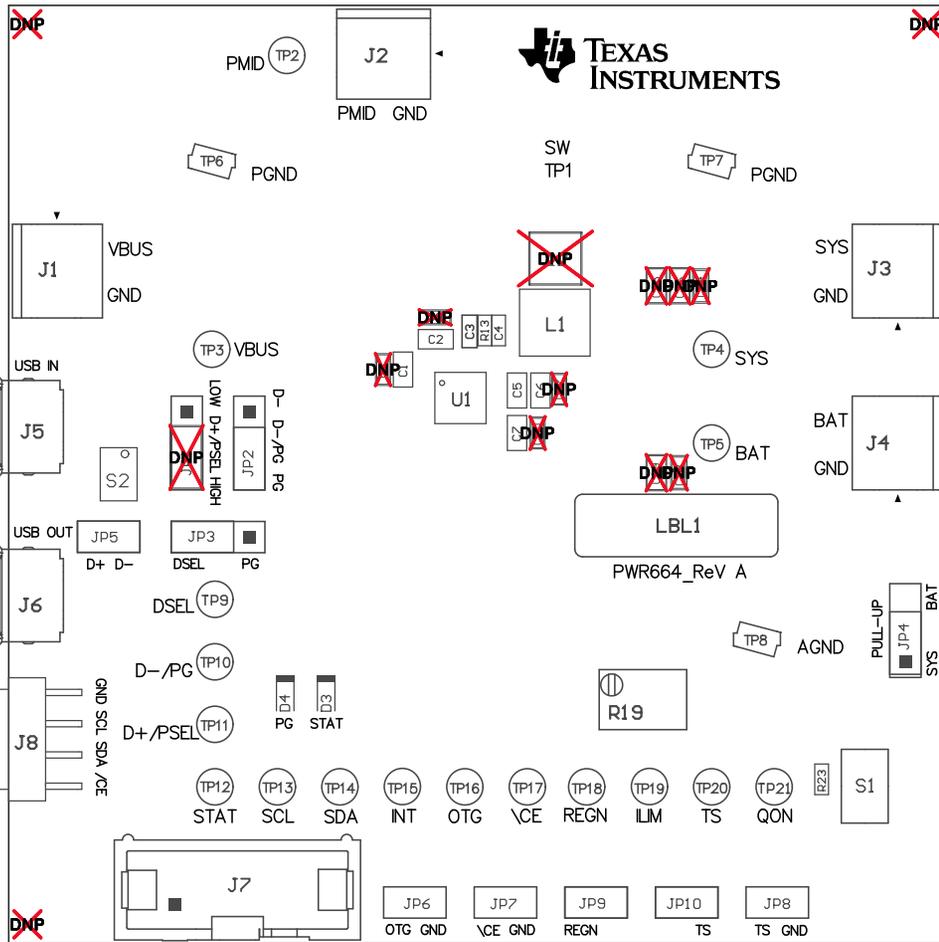


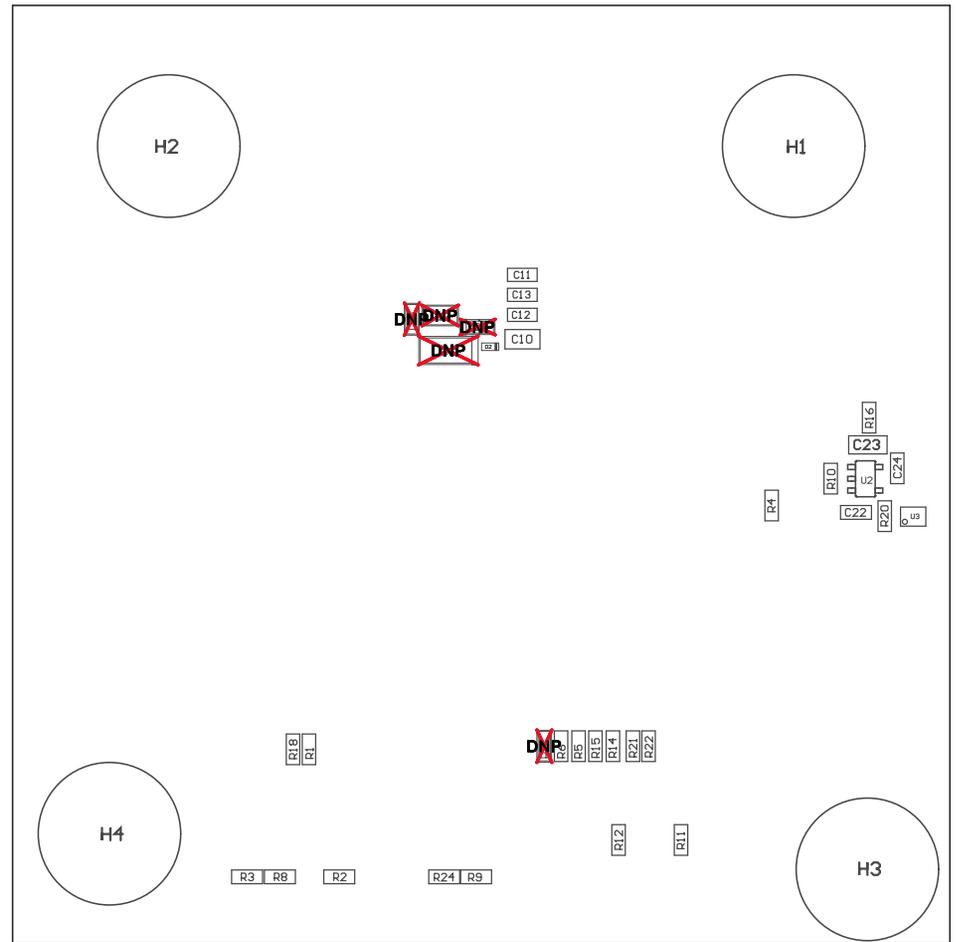
TABLE 1

Variant	Label text
001	BQ25890EVM-664
002	BQ25892EVM-664
003	BQ25895EVM-664

COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
ASSEMBLY VARIANT: 001

TIDA-00589

PCB VIEWED FROM TOP SIDE	BOARD #: PWR664	REV: A	SUN REV:
IGNORE -> Top Overlay			
PLOT NAME =	GENERATED : 02/23/2015	TEXAS INSTRUMENTS	



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
 ASSEMBLY VARIANT: 001

TIDA-00589

PCB VIEWED FROM BOTTOM SIDE	BOARD #: PWR664	REV: A	SUN REV:
	IGNORE -> Bottom Overlay		
PLOT NAME =	GENERATED : 02/23/2015		TEXAS INSTRUMENTS

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